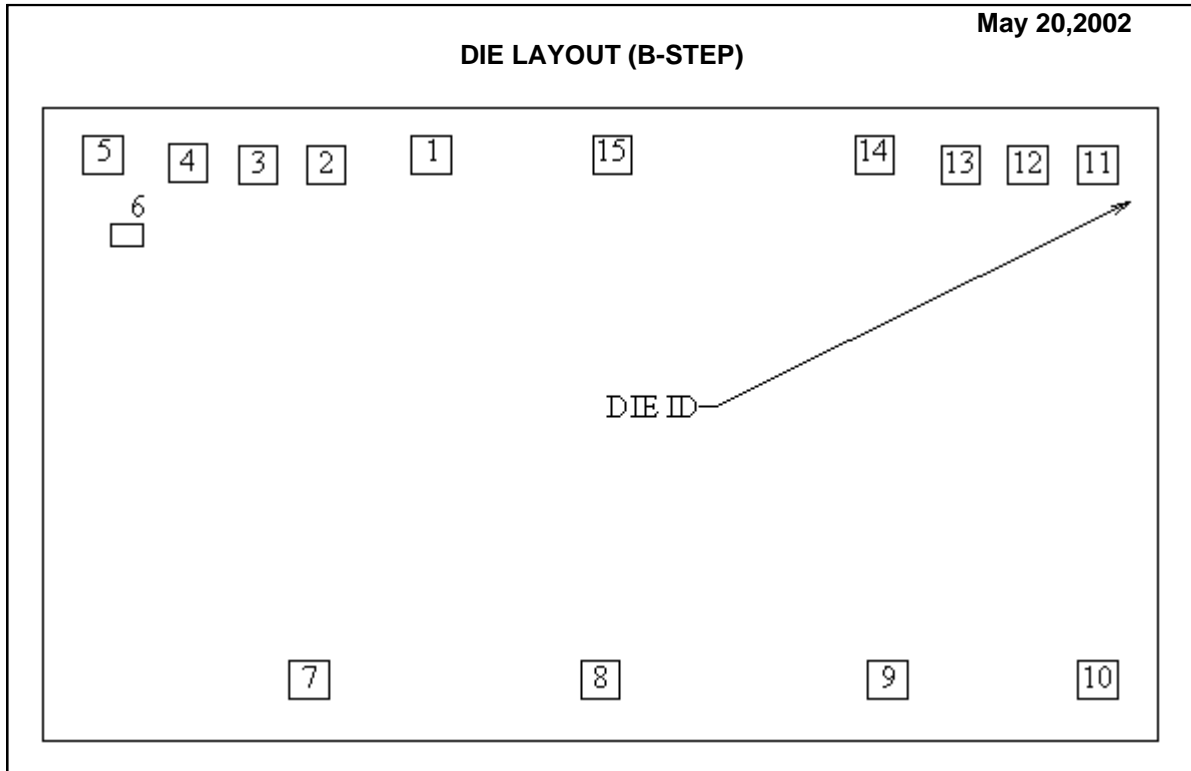


LF412A MDC MWC
LOW OFFSET, LOW DRIFT DUAL JFET INPUT OPERATIONAL AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LF412B	Bond Pad Opening Size (min)	91µm x 91µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	2642µm x 1499µm 104mils x 59mils	Back Side Connection	Floating
Thickness	406µm Nominal		
Min Pitch	498µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES		PAD SIZE		
		X	Y	X	Y	
OUT A	1	-401	639	91	x	91
NC	2	-651	614	90	x	91
NC	3	-813	614	91	x	91
NC	4	-978	619	91	x	91
IN A-	5	-1179	639	91	x	91
NC	6	-1120	450	76	x	53
IN A	7	-691	-605	92	x	91
V-	8	0	-605	92	x	91
IN B+	9	681	-605	92	x	91
IN B-	10	1179	-605	91	x	91
NC	11	1179	614	91	x	91
NC	12	1013	614	91	x	91
NC	13	852	614	90	x	91
OUT B	14	648	639	91	x	91
V+	15	28	639	91	x	91

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